



FOR IMMEDIATE RELEASE

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Visit Tech-X at ICOPS in Chicago

Boulder, CO – June 21, 2011 - Tech-X Corporation invites you to visit our booth (Booth #202) at the 38th International Conference on Plasma Science and 24th Symposium on Fusion Engineering (<https://engineering.purdue.edu/ICOPS2011/>), June 26 - 30, at the Hyatt Regency, McCormick Place in Chicago.

We are proud to present the latest release of our electromagnetic plasma simulation software, VORPAL (<http://vorpall.txcorp.com>). VORPAL 4.2.2 includes improved documentation, simplified installation on all platforms, additional collision models, import of user-defined secondary electron yield data, a new photoemission model, delta-F particles for modeling tokamak geometries, and new field updaters.

Personnel from Tech-X and/or their collaborators will be participating in the following activities:

Session IO1B: Slow-Wave Devices/Intense Beam Microwave Generation (o)
Monday, June 27 10:00-12:00, CC23 AB

10:45 IO1B-3 Three-Dimensional, Time-Dependent Simulation of Inductive Output Tubes, H. Freund, J. Verboncoeur, SAIC, McLean, VA, United States; W. Sessions, NSWC Dahlgren, Dahlgren, VA, United States; B. Jamroz, C. Jhurani, Tech-X Corp., Boulder, CO, United States; L. Ives, T. Bui, Calabazas Creek Research, San Mateo, CA, United States

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Session IP1G: Microwave Plasma Interactions (p)

Poster Session

Monday, June 27 13:00-15:00, CC11 AB

IP1G-44 Modeling of a Tokamak Antenna Module with VORPAL, C. M. Roark, D. N. Smithe, T. M. Austin, S. W. Sides, Tech-X Corporation, Boulder, CO, United States

Session IP2B: Computational Plasma Physics I (p)

Poster Session

Tuesday, June 28 13:00-15:00, CC11 AB

IP2B-13 Integrated Thermal & EM Simulation Capability in the VORPAL Software, D. Smithe, P. Stoltz, Tech-X Corporation, Boulder, CO, United States; H. Wang, G. Cheng, Thomas Jefferson National Accelerator Facility, Newport News, VA, United States

IP2B-14 Particle-in-Cell (PIC) Tools for Simulation of Electrodynamic Bare Tether Plasma Interactions, S. Mahalingam, Y. Choi, P. H. Stoltz, Tech-X Corporation, Boulder, CO, United States; L. P. Rand, J. D. Williams, Mechanical Engineering, Colorado State University, Fort Collins, CO, United States

Session IO4B: Codes & Modeling (o)

Tuesday, June 28 15:00-16:30, CC23 AB

16:30 IO4B-6 Study on Low-Frequency Oscillations in a Gyrotron Using a 3D CFDTD PIC Method, M. C. Lin, D. N. Smithe, Tech-X Corporation, Boulder, CO, United States

Session IP3C: Slow-Wave Devices (p)

Poster Session

Wednesday, June 29 13:00-15:00, CC11 AB

IP3C-15 Compact and Lightweight S-Band TWT for Phased Antenna Array Radar Applications, H. Song, L. Tekamp, Electrical and Computer Engineering, Univ. of Colorado at Colorado Springs, Colorado Springs, CO, United States; F. Francisco, Electron Technology Division, Triton Services Inc., Easton, PA, United States; M. -C. Lin, P. Stoltz, D. Smith, Tech-X Corporation, Boulder, CO, United States; H. J. Kim, G. W. Choi, J. J. Choi, Radio Science and Engineering, Kwangwoon University, Seoul,

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South Korea; S. J. Kim, S. H. Jang, Agency for Defense Development, Daejeon, South Korea

About Tech-X Corporation

Tech-X Corporation is committed to technical excellence and innovation. Our technical staff addresses specific research questions and delivers quantifiable results, culminating in specialized skills, advanced technologies, and commercial products that enable large-scale computing solutions and offer a greater understanding of physical processes.

Among our core competencies is the simulation of processes, devices, and physical systems related to plasma physics, fusion, and accelerator technologies, performed on computer systems ranging from desktops to Grand Challenge class high-performance computers. By creating software for simulations and the infrastructure to support our research development, we are able to increase our understanding of complex physical phenomena. For more information, visit <http://www.txcorp.com>.

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